

GP/2811

PATENT



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Horiuchi et al.  
Serial No.: 09/812,276  
Filed: March 20, 2001  
Title: SEMICONDUCTOR DEVICE  
AND PROCESS OF PRODUCTION  
OF SAME  
Examiner: Patricia M. Costanzo  
Atty Doc. No. 72-01



Commissioner of Patents  
Washington, DC 20231

COVER LETTER WITH CERTIFICATE OF MAILING

Sir:  
Enclose please find the following documents:  
  
(1) Cover Letter with Certificate of Mailing;  
(2) Amendment (3 pages);  
(3) Abstract Of The Disclosure (1 page);  
(4) Clean Copy of Specification Pages 5, 7, and 38;  
(5) Clean Copy of Claim 21; and  
(6) Paul & Paul Postcard to be returned by the PTO.

RECEIVED  
AUG - 8 2002  
TECHNOLOGY CENTER 2800

THE COMMISSIONER IS HEREBY AUTHORIZED TO CHARGE ANY ADDITIONAL FEES ASSOCIATED WITH THIS COMMUNICATION, OR CREDIT ANY OVERPAYMENT, TO PAUL & PAUL DEPOSIT ACCOUNT NO. 16-0750, ORDER NO. 0745.

Respectfully submitted,  
  
John F. McNulty, Esquire  
Registration No. 23,028  
Paul & Paul  
2900 Two Thousand Market Street  
Philadelphia, PA 19103  
(215) 568-4900



#7 / AMTA  
8-15-02  
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Amendment

Sir:

This is in response to the Official Action of May 2, 2002.

Please amend the above-identified application as follows:

Please replace the Abstract Of The Disclosure with the enclosed replacement sheet comprising an Abstract Of The Disclosure with 150 words or fewer.

Please amend the specification as follows:

Page 5, line 5 after "layer and", insert -- forming throughholes in the thickness direction--

Page 7, line 19 after "arranged" insert -- in --.

Page 38, line 15, change "129" to -- 124 --.

NE Replacement pages for pages 5, 7 and 38 are provided herewith.

In the claims:

Re-write claims 21 as follows:

A3 21. (Amended) A semiconductor device as set forth in claim 20, wherein the top surface of said resin member [sealing resin layer] and the back surface of said semiconductor element form substantially the same plane.